

AN-1610 LP5552 Evaluation Board

1 LP5552 Overview

The LP5552 is a PWI™ 2.0 compliant Energy Management Unit for reducing power consumption of stand-alone mobile phone processors such as baseband or applications processors.

The LP5552 contains two advanced, digitally controlled switching regulators for supplying variable voltage to processor core and memory. The device also integrates 5 programmable LDO regulators for powering I/O and PLLs, as well as maintaining memory retention in sleep-mode.

The device is controlled via the PWI 2.0 open-standard interface. The LP5552 operates cooperatively with PowerWise™ technology-compatible processors to optimize supply voltages adaptively over process and temperature variations or dynamically using frequency/voltage pre-characterized look-up tables.

2 Evaluation Board Overview

The LP5552 Evaluation Board, [Figure 1](#), can be operated standalone or from a mainboard such as the PowerWise Evaluation Kit (PEK) or USB2PWI interface board.

The evaluation board ships with the USB2PWI interface board and a graphical user interface (GUI) to easily control the features of the LP5552 from a PC. For information on the GUI, see *AN-1653 User's Graphical User Interface (GUI) for LP555x Evaluation Board PowerWise Technology Compliant Energy Management Unit Application Report* ([SNVA251](#)).

The LP5552 is configured to operate with the following conditions:

Parameter	Default Voltage	Voltage Range	I _{OUT}
V _{IN}	3.6V	2.7 - 4.8V	
V _{CORE1}	1.235V	0.6 - 1.235V	800mA
V _{CORE2}	1.235V	0.6 - 1.235V	800mA
V _{O1}	1.2V	0.7 - 2.2V	100mA
V _{O2}	3.3V	1.5 - 3.3V	250mA
V _{O3}	1.25V	0.6 - 1.35V	50mA (High I _O)
V _{O4}	1.25V	0.6 - 1.35V	50mA (High I _O)
V _{O5}	3.3V	1.2 - 3.3V	250mA

Note that all the regulators can be programmed to different output voltages once the part is active.

The LP5552 can be powered externally (bench supply), or from the PEK or USB2PWI interface board (depending on the mainboard being used). Jumper "VIN SEL" must be set to the appropriate power source.

Jumper	Purpose	Note
VIN SEL	Input voltage selection	MSTR: LP5552 powered from attached mainboard; DEFAULT EXT: LP5552 powered from external supply

There are two additional jumpers on the LP5552 evaluation board. They behave as follows.

Jumper	Purpose	Note
JP1	Disconnect indicator LEDs and PWROK buffer	ON: The PWR ON and PWROK indicators are active; DEFAULT
		OFF: The buffer and LEDs will remain unpowered
JP2	Disconnect GPO pull-up resistors	ON: The 10K pull-up resistors are connected to the GPO pins; DEFAULT
		OFF: The GPO pull-up resistors are disconnected, for use with CMOS outputs

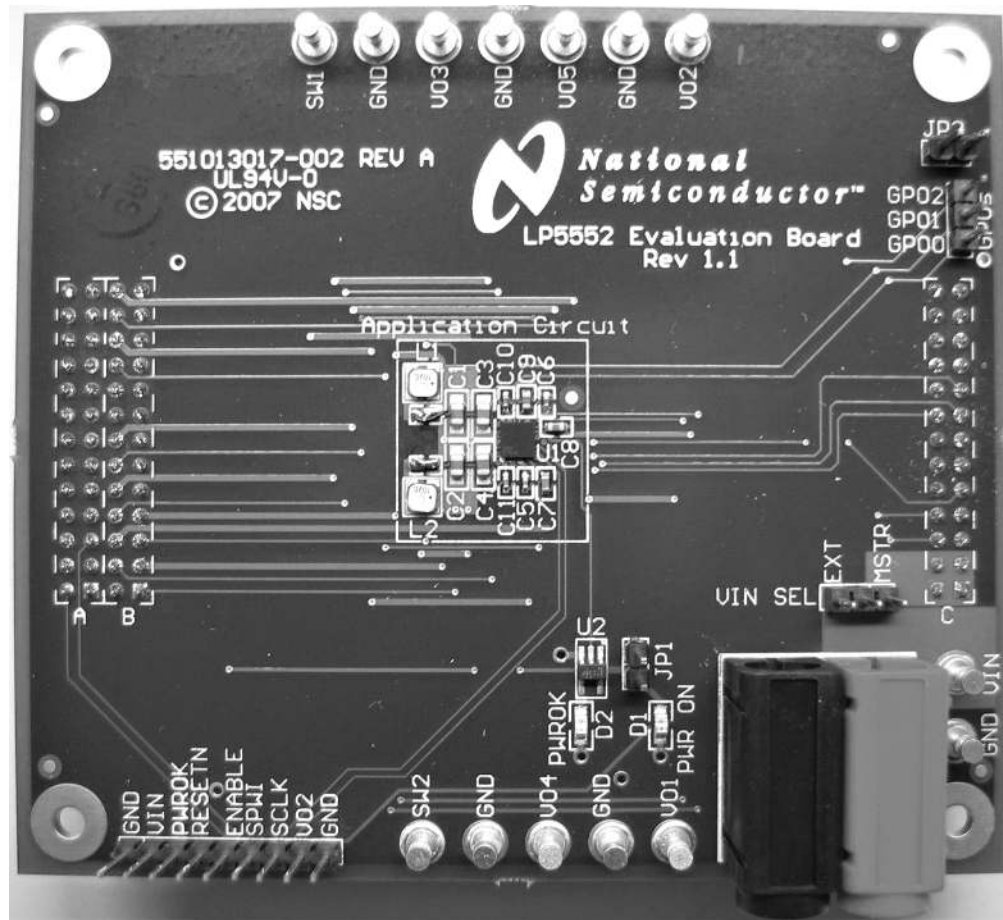


Figure 1. LP5552 Evaluation Board

3 Connecting the LP5552 to the USB2PWI Interface Board

The LP5552 evaluation board can be connected to the USB2PWI interface board for convenient control of the PWI and all the LP5552 functions via a simple register-based GUI. [Figure 2](#) shows the USB2PWI interface board. See AN-1653 for instructions on how to use the GUI.

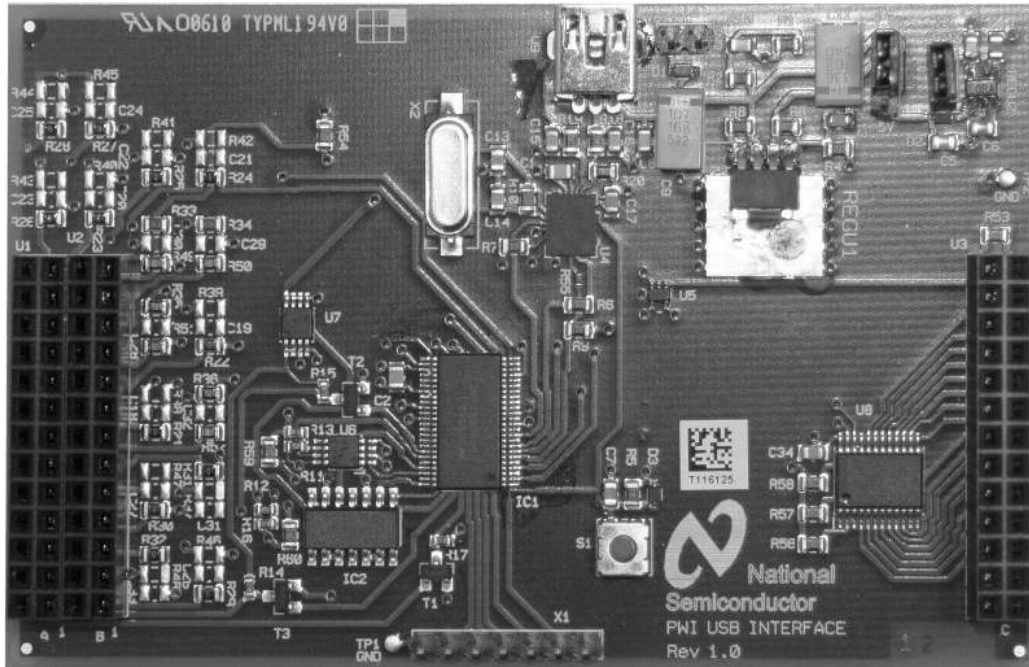


Figure 2. USB2PWI Interface Board

4 Connecting the LP5552 Evaluation Board to an External Controller

All signals related to the PWI signalling environment are available on a 1x9 header on the edge of the board. Although primarily intended for signal inspection, this header also allows for external control of the PWI, used to communicate with the LP5552. The pins are spaced at 100-mil intervals. The pin list of this header is shown in [Table 1](#). Input and output direction is with reference to the LP5552. V_{IN} and V_{O2} are provided as reference voltages to determine the drive levels for the signals RESETN, ENABLE, PWROK, SPWI, and SCLK. The external controller should drive ENABLE and RESETN between V_{IN} and GND, while SPWI and SCLK should be driven between V_{O2} and GND. The PWROK output will have a logic-high output at V_{IN} .

Table 1. Pin Functions

Pin	Function	Type	Description
1	GND	GND	Ground
2	V_{IN}	Output	V_{IN} Sense
3	PWROK	Output	PWROK
4	RESETN	Input	V_{IN} : Active GND: LP5552 in reset
5	ENABLE	Input	V_{IN} : On GND: Disable LP5552
6	SPWI	Input/Output	PWI Data
7	SCLK	Input	PWI Clock
8	V_{O2}	Output	V_{O2} Sense
9	GND	GND	Ground

5 Connecting the LP5552 Evaluation Board to the PEK

The PEK is designed to quickly and easily control the LP5552 for PowerWise Interface (PWI) compliance testing. [Figure 3](#) shows the PEK. See the PEK User's Guide for more information.

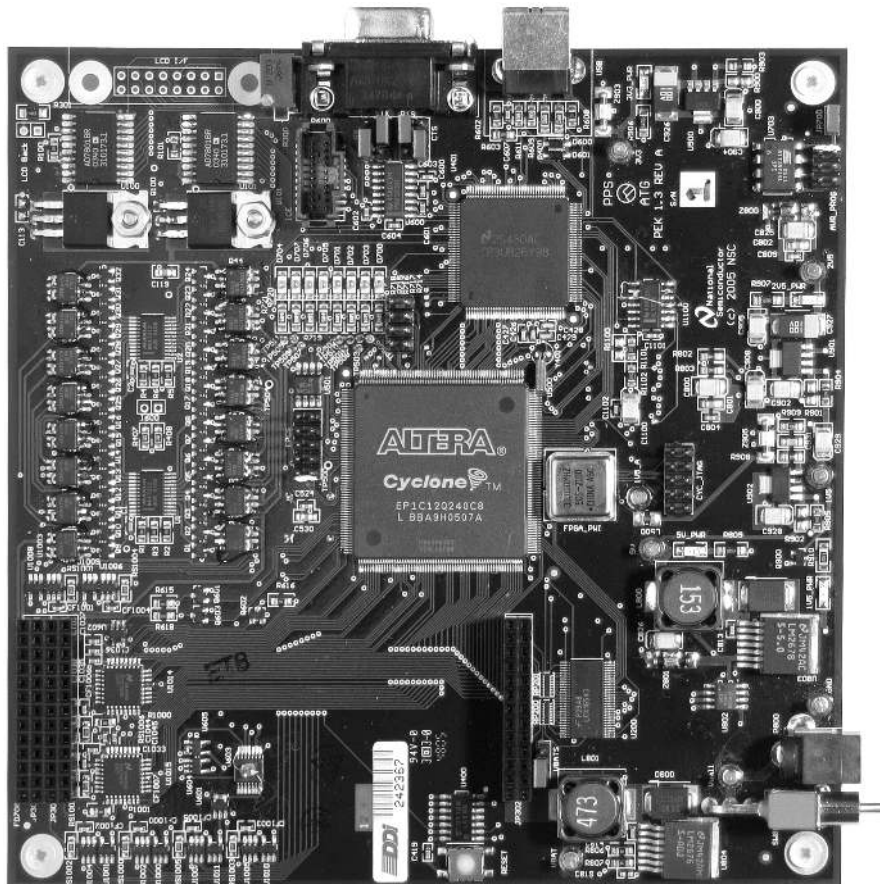


Figure 3. PowerWise Evaluation Kit (PEK)

6 PCB Layout Considerations

The evaluation board is comprised of four layers. See [Section 8](#) for layout artwork. From top to bottom they are:

1. Top, component side
2. Ground plane
3. V_{IN} plane
4. Bottom

Being a very high performance EMU in a small physical package requires that some care be taken when placing the IC into the application circuit. The breakout of the IC should be done as similarly to the example artwork as possible. Everything on the outer ring of the DSBGA should be routed on the component layer while microvias are used to escape the remaining signals on the adjacent layer. The layout should be done in the following order to ensure best performance:

1. Switchers
2. PowerWise Interface
3. Input Caps
4. LDO Output Caps
5. Any remaining layout

For good performance of the circuit, it is essential to place the input and output capacitors as close as physically possible to the associated pin.

Sensitive components should be placed far from those components with high switching currents.

It is a good practice to minimize high-current and switching-current paths.

6.1 DC/DC Buck Switching Regulators

Due to the high switching currents and accuracy of the LP5552, this is the most crucial aspect of the layout. And because the switchers are almost a complete mirror image of one another on the part, the design is most easily placed symmetrically about the part.

The 10 μ F input capacitors should be placed first, as near to PVDDx and PGNDx as possible. PVDDx (pins A6 and A1) are the voltage rails for the high-side power FETs. PGNDx (pins A4 and A3) are the return paths for the low-side power FETs. As seen with C3 and C4 in the artwork, these components have their associated pads very near the pins that they will decouple. These capacitors are important in sourcing charge during switching events.

The 10 μ F output capacitors are the next components to be placed. They can be seen in the artwork as C1 and C2. Best performance of the LP5552 will be realized by maintaining tight physical coupling of the grounds of the input capacitor, output capacitor and PGND pin for each switcher. By placing the input/output capacitors as depicted, a channel is created that will allow routing the switching node out to the inductor between the pads of the input and output capacitors.

The output magnetics should be placed in a way that best allows the switching node, output node, and supplied load to be routed easily. The inductors, and associated connections, are the least sensitive to layout variation. Note that the evaluation board contains a 0-ohm series resistor between the switching node and the inductor. This is included as a means to more easily make measurements on the evaluation board and is NOT required in the application circuit.

Once placement of these components has been completed, the associated wiring/routing should be done. The switching nodes should be routed to their associated inductors. Next, a ground polygon and/or plane should be used to tie all capacitor grounds together and to the PGNDs. An example of this is shown in the board artwork. Here we have a pour on the top layer that connects everything together, and we stitched it into the ground plane to maintain the same potential at both points. There will be quite a bit of switching current in this area so it should be physically isolated from other sensitive circuitry. Once the ground connections are in place, proceed to routing the V_{IN} connections. Finally, the FBx and RGND contacts should be routed. The RGND should tie into a quiet location that will track the potential of the PGND pins. On the evaluation board layout, this connection was made at the edge of the ground polygon on the top layer. The FB lines should closely match the RGND routing to reduce the inductive loop of this pair. The FB and RGND lines make up a high-side and low-side sense connection to maintain the accuracy of the switcher outputs. The FB line should cross the switching trace as close to perpendicular as possible and tie into the output node of the regulator. Low impedance power connections should be maintained for all of these connections.

6.2 PowerWise Interface Routing

The PowerWise SCLK and SPWI lines should then be routed to the appropriate master in the system. If this is a multi-master and/or multi-slave system, care should be taken in matching the trace lengths of all segments of the PWI bus. Additionally, the designer must ensure that the electrical characteristics of the interconnect do not violate the restrictions in the PowerWise Interface 2.0 specification.

6.3 Input Capacitors

Any additional input decoupling capacitors that are part of the design should now be placed and routed. In the case of the evaluation board, this includes capacitors C5 and C6. They are general purpose caps and are tied directly to the V_{IN} plane on the board. It is not mandatory to include additional bypass caps, however it is recommended. Low impedance connections are required to allow the capacitors to function at their peak performance. Regardless of any decoupling capacitors, EVERY V_{IN} CONNECTION SHOULD HAVE ITS OWN ROUTING FROM THE SOURCE. Vias and/or traces should NOT be shared amongst V_{IN} pins. The PVDDx pins especially should have their own separate supply connections.

6.4 LDO Output Capacitors

This step involves placing the output capacitors of the LDO regulators. If an LDO will not be used, it is not necessary to place its output capacitor in the design. These capacitors should be placed as physically close to the LP5552 IC as possible. Again, use low-impedance connections to the output capacitors for best performance.

7 Bill of Materials

Item	Part Value	Part Number	Footprint	Description	Mfg.
A	2 x 13 Pin Array	9-146252-0-13	DIP-26	Mainboard Connector	AMP/Tyco
B	2 x 13 Pin Array	9-146252-0-13	DIP-26	Mainboard Connector	AMP/Tyco
C	2 x 13 Pin Array	9-146252-0-13	DIP-26	Mainboard Connector	AMP/Tyco
CA1	NL		0402	AVDD1 Bypass Cap	N/A
CA2	NL		0402	AVDD2 Bypass Cap	N/A
C1	10 μ F	LMK212BJ106KD	0805	SW1 Output Cap	Taiyo Yuden
C2	10 μ F	LMK212BJ106KD	0805	SW2 Output Cap	Taiyo Yuden
C3	10 μ F	LMK212BJ106KD	0805	SW1 Input Cap	Taiyo Yuden
C4	10 μ F	LMK212BJ106KD	0805	SW2 Input Cap	Taiyo Yuden
C5	0.1 μ F/16V/X5R/10%		0402	General Bypass Cap	N/A
C6	0.1 μ F/16V/X5R/10%		0402	General Bypass Cap	N/A
C7	2.2 μ F/10V/X5R/10%		0603	LDO1 Output Cap	N/A
C8	4.7 μ F/10V/X5R/10%		0603	LDO2 Output Cap	N/A
C9	4.7 μ F/10V/X5R/10%		0603	LDO5 Output Cap	N/A
C10	1.0 μ F/10V/X5R/10%	LMK105BJ105KV	0402	LDO3 Output Cap	Taiyo Yuden
C11	1.0 μ F/10V/X5R/10%	LMK105BJ105KV	0402	LDO4 Output Cap	Taiyo Yuden
C12	0.1 μ F/16V/X5R/10%		0402	PWROK Buffer Bypass Cap	N/A
L1	1 μ H	LPS3010-102ML	LPS30xx	SW1 Output Inductor	Coilcraft
L2	1 μ H	LPS3010-102ML	LPS30xx	SW2 Output Inductor	Coilcraft
PWR ON	Red LED	LTST-C171KRKT	0805	Red Power On Indicator	Lite-On
PWROK	Green LED	LTST-C170KGKT	0805	Green PWROK Indicator	Lite-On
R1	NL		0603	Pull-up for ENABLE	N/A
R2	NL		0603	Pull-up for RESETN	N/A
R3	10K/0.1W/5%	CRCW060310K0JN	0603	SA1 Pull-down	Vishay/Dale
R4	10K/0.1W/5%	CRCW060310K0JN	0603	SA2 Pull-down	Vishay/Dale
R5	10K/0.1W/5%	CRCW060310K0JN	0603	SA3 Pull-down	Vishay/Dale
R6	10K/0.1W/5%	CRCW060310K0JN	0603	GPO0 Pull-up	Vishay/Dale
R7	10K/0.1W/5%	CRCW060310K0JN	0603	GPO1 Pull-up	Vishay/Dale
R8	10K/0.1W/5%	CRCW060310K0JN	0603	GPO2 Pull-up	Vishay/Dale
R9	1.5K/0.1W/5%	CRCW06031K50JN	0603	Mainboard Presence Detect	Vishay/Dale
R10	1.5K/0.1W/5%	CRCW06031K50JN	0603	Mainboard Presence Detect	Vishay/Dale
R11	240-ohm/0.1W/5%	CRCW0603240RJN	0603	Red LED Current Limit Res	Vishay/Dale
R12	160-ohm/0.1W/5%	CRCW0603160RJN	0603	Green LED Current Limit Res	Vishay/Dale
R13	0-ohm/0.063W/5%		0402	RGND Isolation Res	N/A
SW1_O	0-ohm/0.1W/5%		0603	Measurement Pads SW1	N/A
SW2_O	0-ohm/0.1W/5%		0603	Measurement Pads SW2	N/A
U1	LP5552 PMIC	LP5552	DSBGA-36	PowerWise PMIC	Texas Instruments
U2	Tri-State Buffer	NC7SZ126M5	SOT23-5	PWROK LED Buffer	Fairchild Semi

8 Layout Artwork

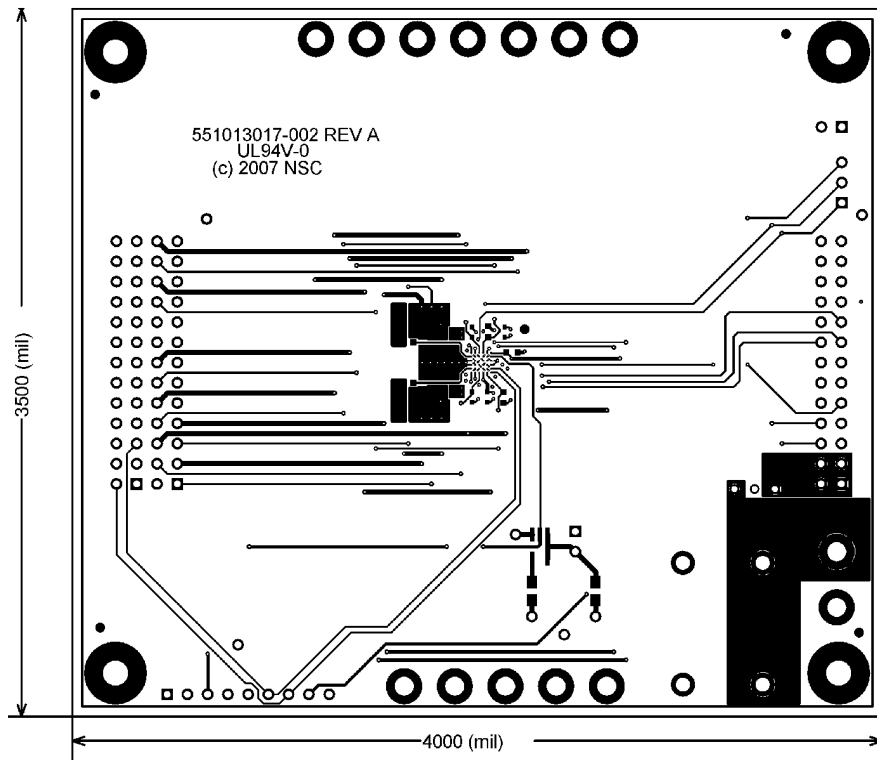


Figure 4. Top Layer

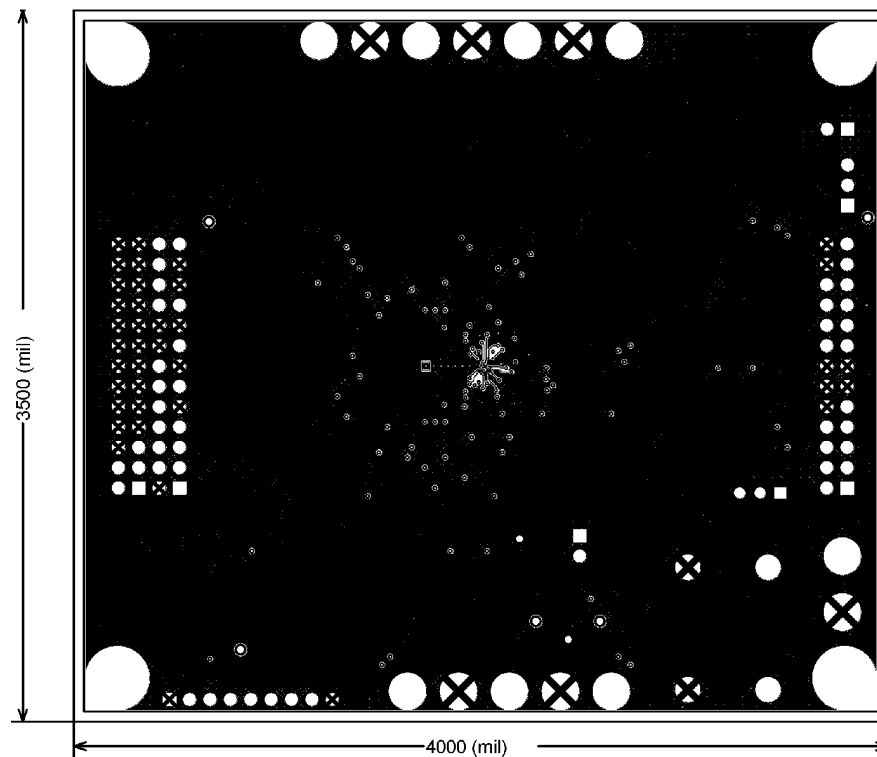


Figure 5. L2, Ground Plane

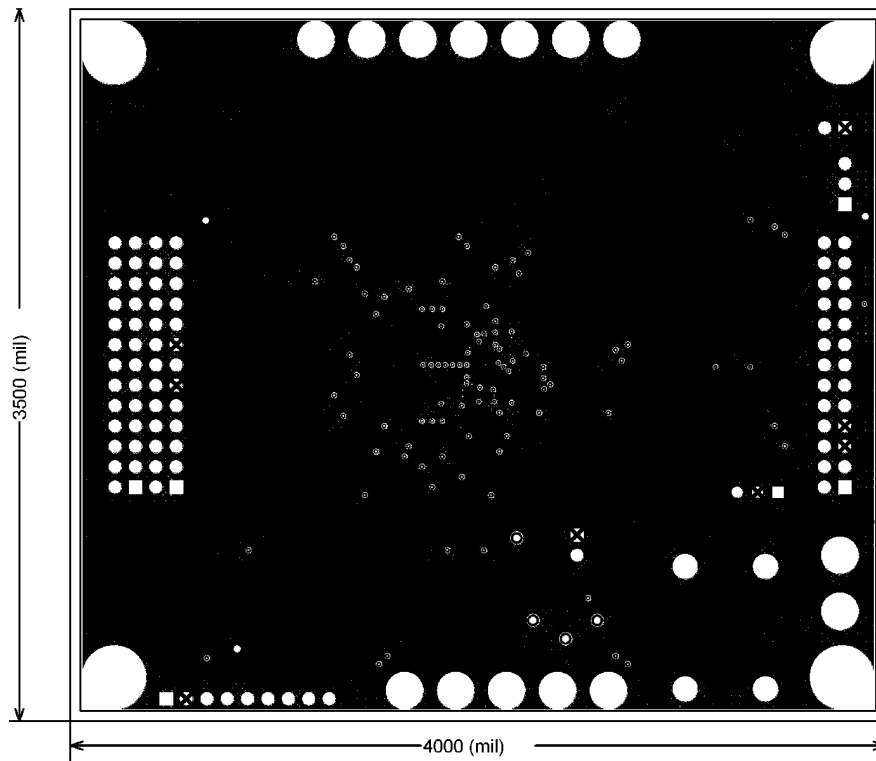


Figure 6. L3, V_{IN} Plane

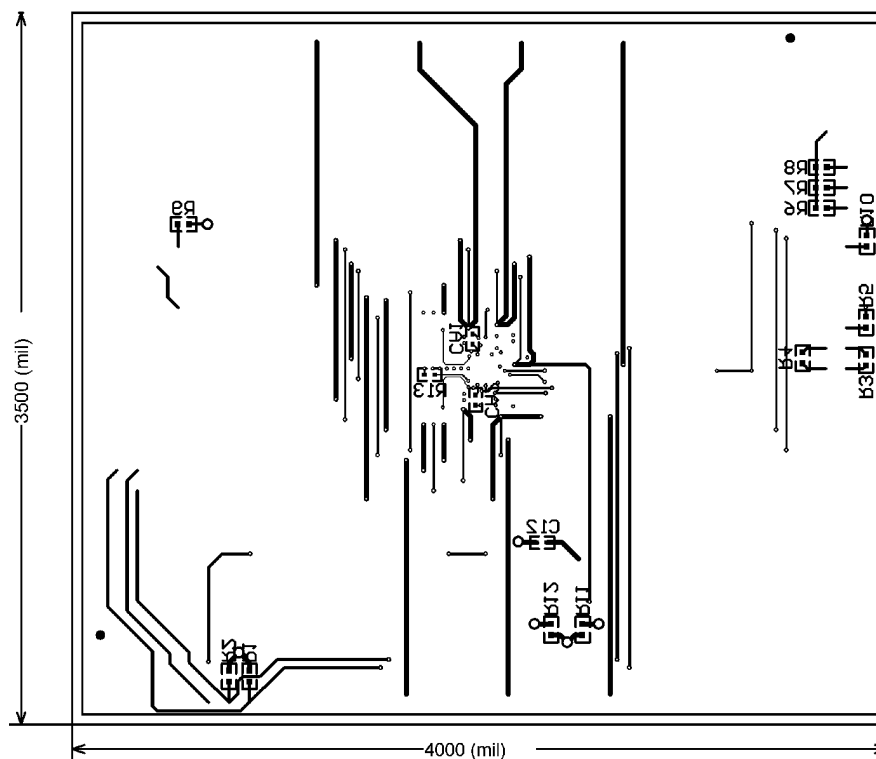


Figure 7. Bottom Layer

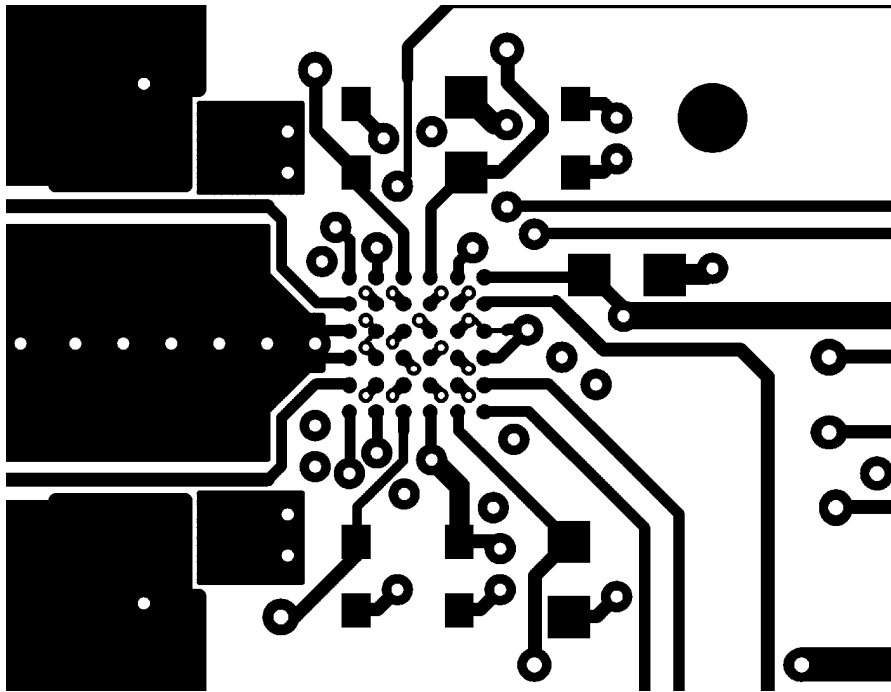


Figure 8. Top Layer Close Up

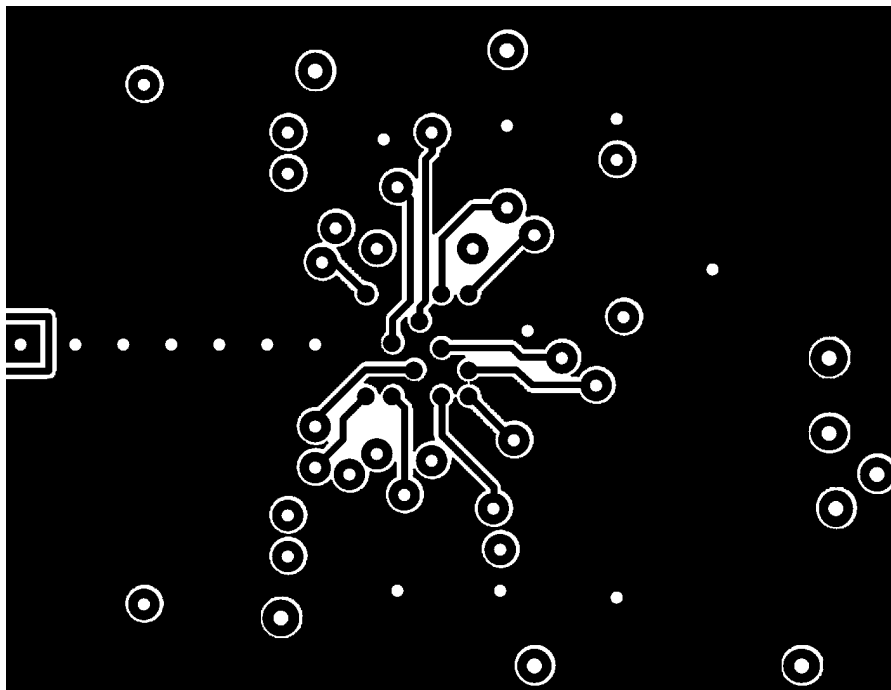


Figure 9. L2 Close Up

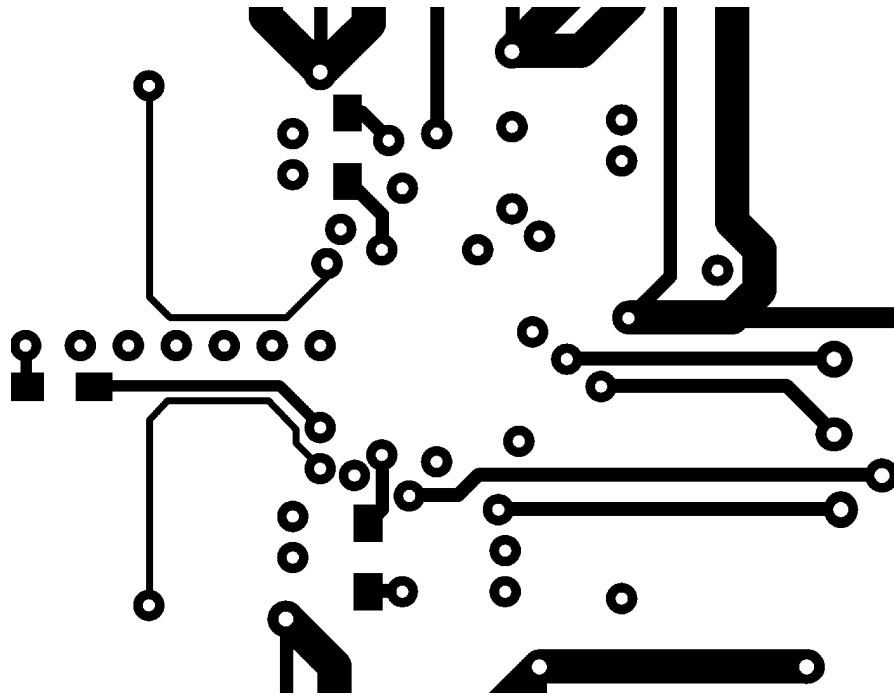


Figure 10. Bottom Layer Close Up

9 Evaluation Board Schematic

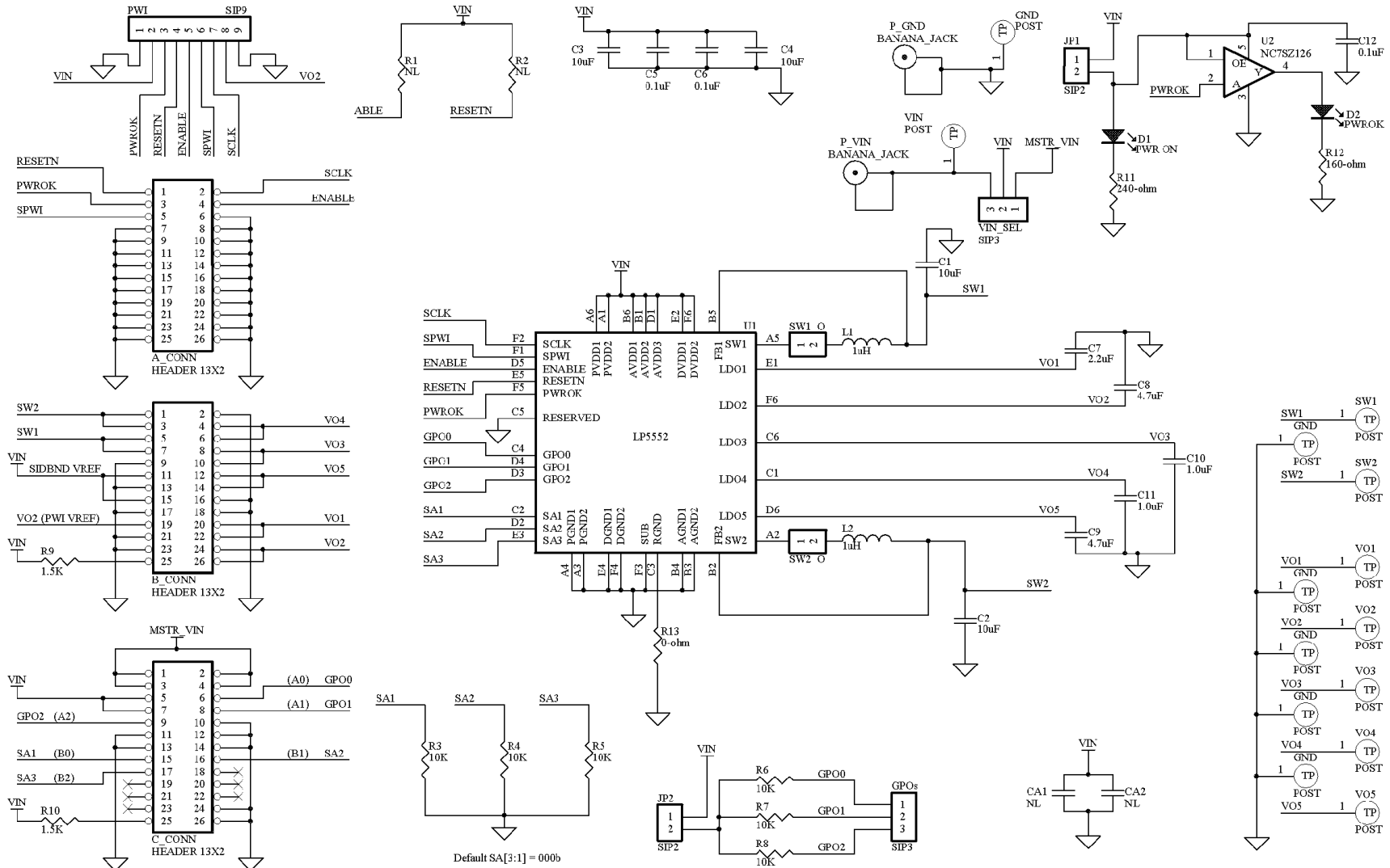


Figure 11. LP5552 Evaluation Board Schematic

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